

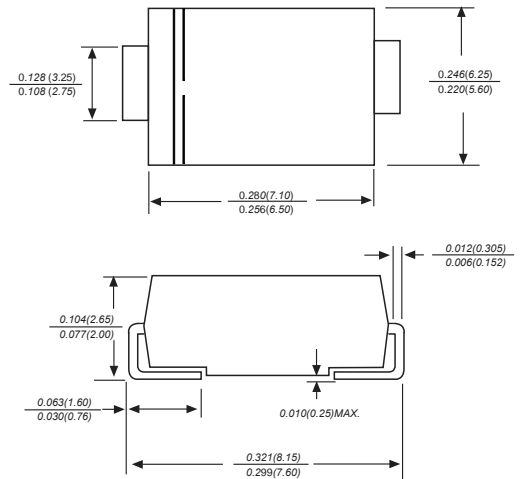
## SURFACE MOUNT GENERAL RECTIFIER

### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:  
250 °C/10 seconds at terminals



### DO-214AB/SMC



Dimensions in inches and (millimeters)

### Mechanical Data

Case: JEDEC DO-214AB/SMC molded plastic body  
 Terminals: Solderable per MIL-STD-750, Method 2026A  
 Polarity: Polarity symbol marking on body  
 Mounting Position: Any  
 Weight: 0.0077 ounce, 0.22grams

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	MDD S3AC	MDD S3BC	MDD S3DC	MDD S3GC	MDD S3JC	MDD S3KC	MDD S3MC	UNITS
Marking Code									
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{(AV)}$	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	90							A
Maximum instantaneous forward voltage at 3.0A	$V_F$	1.0							V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	$I_R$	5 100							$\mu\text{A}$
Typical junction capacitance (NOTE 1)	$C_J$	40							pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$ $R_{\theta JC}$	40 16							$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 2. P.C.B. mounted with 2.0"x2.0" (5.0x5.0cm) copper pad areas

## Typical Characteristics

Fig.1 Forward Current Derating Curve

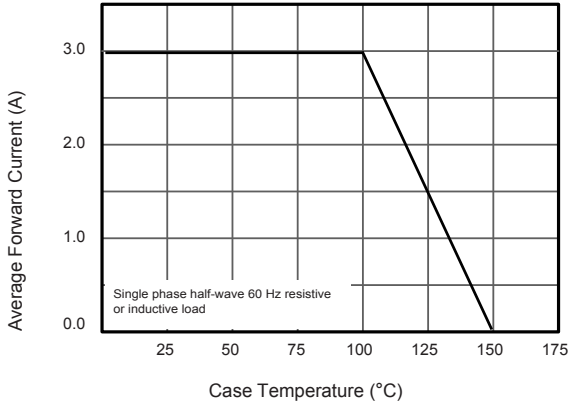


Fig.2 Typical Reverse Characteristics

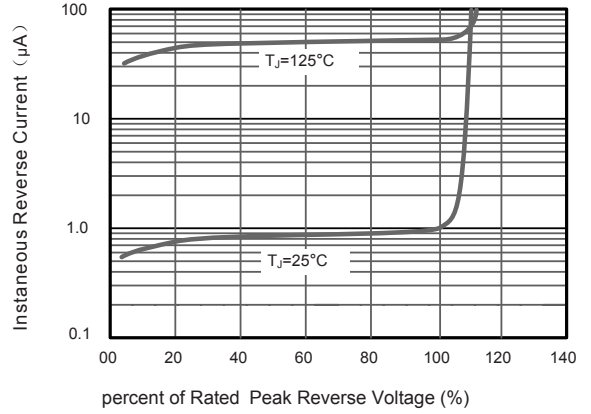


Fig.3 Typical Forward Characteristic

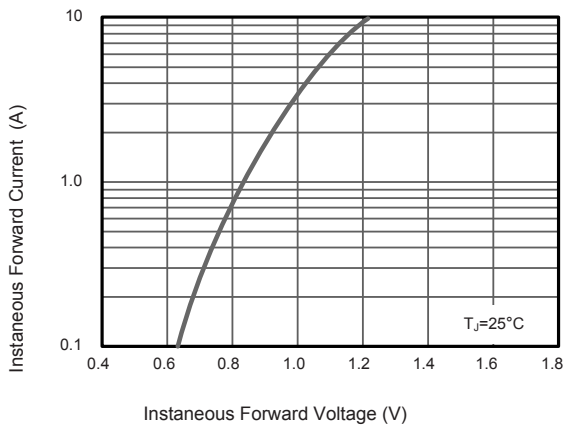


Fig.4 Typical Junction Capacitance

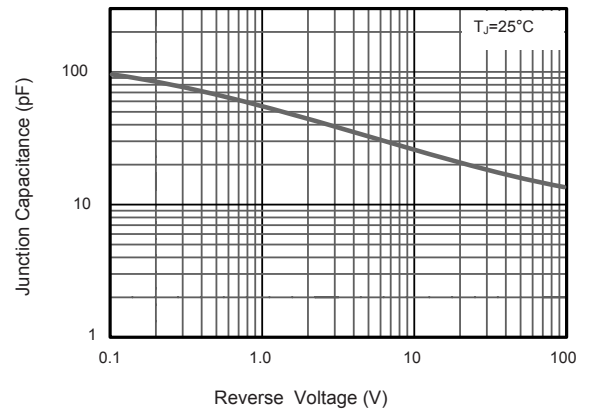
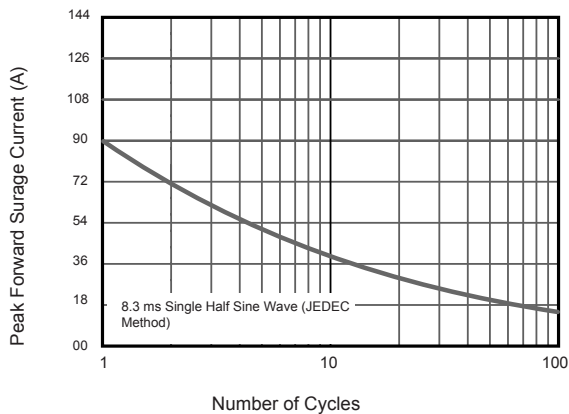
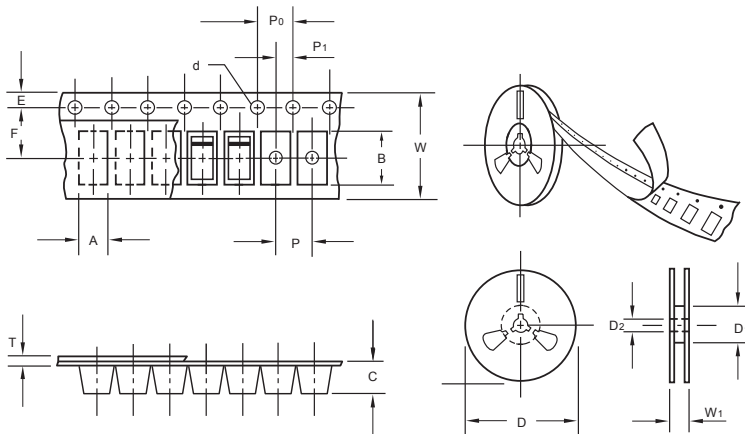


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



## Packing information



unit:mm

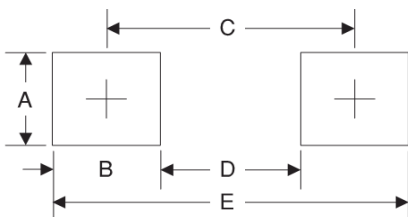
Item	Symbol	Tolerance	SMC
Carrier width	A	0.1	6.15
Carrier length	B	0.1	8.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D <sub>1</sub>	min	50.00
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	16.00
Reel width	W <sub>1</sub>	1.0	16.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA. (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC	13"	3,000	4.0	6000	340*350*47	330	370*370*370	42000	14.0

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	4.3	0.170
B	4.1	0.160
C	7.9	0.311
D	3.8	0.150
E	12	0.472

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